

**IN THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Cancelled)

2. (Currently Amended) The semiconductor integrated circuit module according to claim 417, wherein

said power supply module comprises

a power supply chip unit or a power supply chip unit and peripheral components thereof and

a plurality of electrodes; and

said package is provided with electrodes on the surface thereof; and

said power supply module is mounted on said package and power is supplied from said power supply module to said package by electrically connecting said electrodes to the electrodes of said power supply module.

3. (Cancelled)

4. (Original) The semiconductor integrated circuit module according to claim 2, further comprises:

an interface between said semiconductor integrated circuit sealed by said package and said power supply module; and

bi-directional control function between said semiconductor integrated circuit and said power supply module.

5. (Original) The semiconductor integrated circuit module according to claim 4, wherein said power supply module is removable from said package.

6. (Original) The semiconductor integrated circuit module according to claim 2, wherein said semiconductor integrated circuit module has a structure that enables itself to install a heat sink after said power supply module was mounted.

7. (Original) The semiconductor integrated circuit module according to claim 6, wherein said power supply module has an opening and said heat sink can be installed via said opening.

8. (Original) The semiconductor integrated circuit module according to claim 2, wherein the output voltage of said power supply module is lower than the input voltage of said package.

9. – 16. (Cancelled)

17. (New) A semiconductor integrated circuit module, comprising:  
a substrate;  
a semiconductor integrated circuit;  
a semiconductor package sealing the semiconductor integrated circuit;

a plurality of first bonding wires, in the semiconductor package, electrically connected to the semiconductor integrated circuit;

a plurality of solder balls connecting the semiconductor package to the substrate;

a first conductive throughhole, in the semiconductor package, connected to one of the plurality of solder balls and inputting power from the substrate via said one solder ball;

a first electrode connected to the first conductive throughhole and inputting power to the semiconductor integrated circuit from the substrate through a first path comprised of said one solder ball, the first conductive throughhole the first electrode and the plurality of first bonding wires.;

a power supply module mounted on an upper surface of said semiconductor package and supplying power to said semiconductor package;

a second electrode connected to the power supply module and supplying power from the power supply module;

a second conductive throughhole, in the semiconductor package, connected to the second electrode and supplying power from the second electrode; and

a second bonding wire, in the semiconductor package, connected to the second conductive throughhole and the semiconductor integrated circuit, and supplying power to said semiconductor integrated circuit from the power supply module through a second path comprised of the second electrode, the second conductive throughhole and the second bonding wire.

18. (New) The semiconductor integrated circuit module according to claim 17, wherein said substrate includes a plurality of inner layers.

19. (New) A semiconductor integrated circuit module, comprising:

- a substrate;
- a semiconductor integrated circuit mounted on said substrate;
- a semiconductor package sealing the semiconductor integrated circuit , said semiconductor package including structural components of a power supply module to supply power to said semiconductor package, said power supply module being mounted on an upper surface of the semiconductor package;
- a plurality of first bonding wires, in the semiconductor package, electrically connected to the semiconductor integrated circuit;
- a plurality of solder balls connecting the semiconductor package to the substrate;
- a first conductive throughhole, in the semiconductor package, connected to one of the plurality of solder balls and inputting power from the substrate via said one solder ball;
- a first electrode connected to the first conductive throughhole and inputting power to the semiconductor integrated circuit from the substrate through a first path comprised of said one solder ball, the first conductive throughhole the first electrode and the plurality of first bonding wires;
- a second electrode connected to the power supply module and supplying power from the power supply module;

a second conductive throughhole, in the semiconductor package, connected to the second electrode and supplying power from the second electrode; and

a second bonding wire, in the semiconductor package, connected to the second conductive throughhole and the semiconductor integrated circuit, and supplying power to said semiconductor integrated circuit from the power supply module through a second path comprised of the second electrode, the second conductive throughhole and the second bonding wire.

20. (New) A semiconductor integrated circuit module according to claim 19, wherein said substrate includes a plurality of inner layers.